

**Abstract of the Disclosure**

**SEMICONDUCTOR DEVICE AND METHOD FOR MANUFACTURE THEREOF**

5           In a semiconductor device, a first semiconductor including  
a substrate, and a semiconductor chip disposed on the major surface  
of the substrate and sealed with a resin; a wiring board; spacers  
disposed between the wiring board and the substrate; and a second  
semiconductor. At this time, the second semiconductor is  
10 electrically connected to the wiring board and disposed in the  
space formed by the wiring board, the substrate, and the spacer.  
The spacer is disposed so as to the first semiconductor to the  
wiring board electrically.